

Class	Subclass
ISSUE CLASSIFICATION	



PATENT NUMBER
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# U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
MA SCANNED UKm102 AA	

APPLICATION NO. 09/920911	CONT/PRIOR	CLASS 438	SUBCLASS 275	ART. UNIT 2812	EXAMINER Booth
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APPLICANTS  
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TITLE  
Thermal compensation method for forming semiconductor integrated circuit microelectronic fabrication

PTO-2040  
12/99

ISSUING CLASSIFICATION									
ORIGINAL				CROSS REFERENCE(S)					
CLASS		SUBCLASS		CLASS		SUBCLASS (ONE SUBCLASS PER BLOCK)			
INTERNATIONAL CLASSIFICATION									

☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.  <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Assistant Examiner) _____ (Date)  _____ (Primary Examiner) _____ (Date)			<b>NOTICE OF ALLOWANCE MAILED</b>	
				<b>ISSUE FEE</b>	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			Amount Due	Date Paid
				<b>ISSUE BATCH NUMBER</b>	

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